

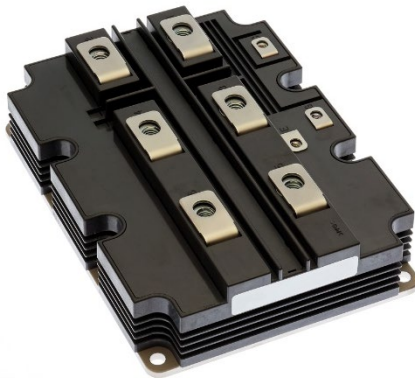
< High Voltage Insulated Gate Bipolar Transistor : HVIGBT >

CM900HG-130X

HIGH POWER SWITCHING USE
INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

CM900HG-130X



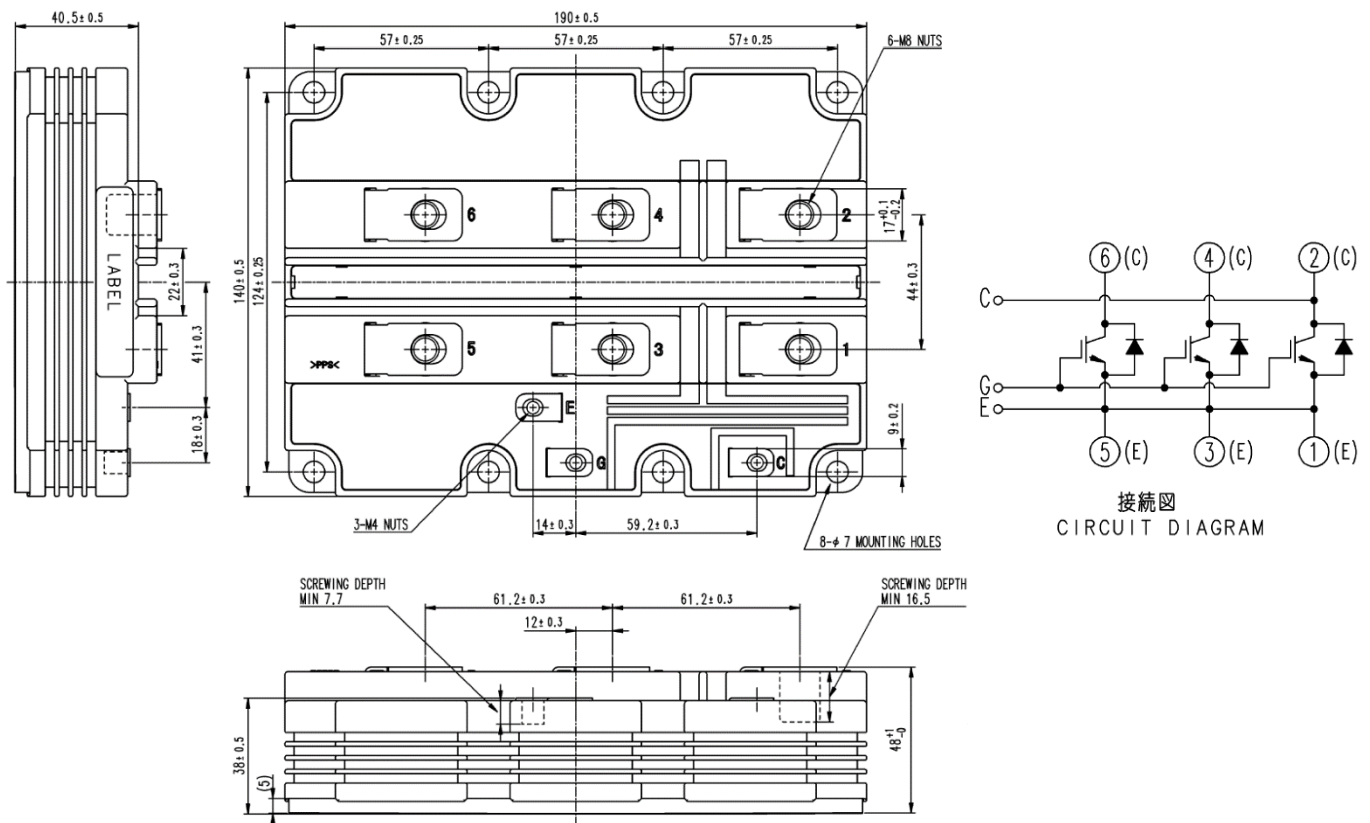
- I_C900A
- V_{CES}6500V
- 1-element in a Pack
- High Insulated Type
- CSTBT™(III) / RFC Diode
- AISiC Baseplate
- UL recognized under UL1557

APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



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MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V_{CES}	Collector-emitter voltage	$V_{GE} = 0V, T_J = 150^{\circ}C$	6500	V
		$V_{GE} = 0V, T_J = 25^{\circ}C$	6300	
		$V_{GE} = 0V, T_J = -50^{\circ}C$	5700	
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_J = 25^{\circ}C$	± 20	V
I_C	Collector current	DC, $T_c = 115^{\circ}C$	900	A
I_{CRM}		Pulse (Note 1)	1800	A
I_E	Emitter current (Note 2)	DC, $T_c = 95^{\circ}C$	900	A
I_{ERM}		Pulse (Note 1)	1800	A
P_{tot}	Maximum power dissipation (Note 3)	$T_c = 25^{\circ}C$, IGBT part	12500	W
V_{iso}	Isolation voltage	RMS, sinusoidal, $f = 60Hz, t = 1 \text{ min.}$	10200	V
Q_{PD}	Partial discharge	$V_1 = 6900 \text{ Vrms}, V_2 = 5100 \text{ Vrms}, 60 \text{ Hz}$	10	pC
T_J	Junction temperature		$-50 \sim +150$	$^{\circ}C$
T_{jop}	Operating junction temperature		$-50 \sim +150$	$^{\circ}C$
T_{stg}	Storage temperature		$-55 \sim +150$	$^{\circ}C$
t_{psc}	Short circuit pulse width	$V_{CC} = 4500V, V_{CE} \leq V_{CES}, V_{GE} = 15V, T_J = 150^{\circ}C$	10	μs

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
I_{CES}	Collector cutoff current	$V_{CE} = V_{CES}, V_{GE} = 0V$	$T_J = 25^{\circ}C$	—	6.0	mA
			$T_J = 125^{\circ}C$	—	5.0	
			$T_J = 150^{\circ}C$	—	150.0	
$V_{GE(th)}$	Gate-emitter threshold voltage	$V_{CE} = 10V, I_C = 90mA, T_J = 25^{\circ}C$	6.5	7.0	7.5	V
I_{GES}	Gate leakage current	$V_{GE} = V_{GES}, V_{CE} = 0V, T_J = 25^{\circ}C$	-0.5	—	0.5	μA
C_{ies}	Input capacitance	$V_{CE} = 10V, V_{GE} = 0V, f = 100kHz$ $T_J = 25^{\circ}C$	—	151	—	nF
C_{oes}	Output capacitance		—	6.3	—	nF
C_{res}	Reverse transfer capacitance		—	0.8	—	nF
Q_G	Total gate charge	$V_{CC} = 3600V, I_C = 900A, V_{GE} = \pm 15V$	—	9.9	—	μC
V_{CEsat}	Collector-emitter saturation voltage	$I_C = 900A$ (Note 4) $V_{GE} = 15V$	$T_J = 25^{\circ}C$	—	2.50	V
			$T_J = 125^{\circ}C$	—	3.20	
			$T_J = 150^{\circ}C$	—	3.30	
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 3600V$ $I_C = 900A$ $V_{GE} = \pm 15V$ $R_{G(on)} = 4.3\Omega$ $L_s = 150nH$ Inductive load	$T_J = 150^{\circ}C$	—	1.45	μs
t_r	Rise time		$T_J = 150^{\circ}C$	—	0.50	μs
$E_{on(10\%)}$	Turn-on switching energy (per pulse) (Note 5)		$T_J = 25^{\circ}C$	—	6.10	J
E_{on}	Turn-on switching energy (per pulse) (Note 6)		$T_J = 125^{\circ}C$	—	6.60	
			$T_J = 150^{\circ}C$	—	7.50	
$t_{d(off)}$	Turn-off delay time		$T_J = 25^{\circ}C$	—	6.30	J
			$T_J = 125^{\circ}C$	—	7.00	
			$T_J = 150^{\circ}C$	—	7.90	
t_f	Fall time	$V_{CC} = 3600V$ $I_C = 900A$ $V_{GE} = \pm 15V$ $R_{G(off)} = 30\Omega$ $L_s = 150nH$ Inductive load	$T_J = 25^{\circ}C$	—	5.90	μs
			$T_J = 125^{\circ}C$	—	7.00	
			$T_J = 150^{\circ}C$	—	7.00	
$E_{off(10\%)}$	Turn-off switching energy (per pulse) (Note 5)		$T_J = 25^{\circ}C$	—	0.50	μs
			$T_J = 125^{\circ}C$	—	1.00	
			$T_J = 150^{\circ}C$	—	1.00	
E_{off}	Turn-off switching energy (per pulse) (Note 6)		$T_J = 25^{\circ}C$	—	3.60	J
			$T_J = 125^{\circ}C$	—	5.80	
			$T_J = 150^{\circ}C$	—	6.00	
E_{off}	Turn-off switching energy (per pulse) (Note 6)		$T_J = 25^{\circ}C$	—	3.70	J
			$T_J = 125^{\circ}C$	—	6.00	
			$T_J = 150^{\circ}C$	—	6.20	

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Symbol	Item	Conditions		Limits			Unit
				Min	Typ	Max	
V _{EC}	Emitter-collector voltage (Note 2)	I _E = 900A (Note 4) V _{GE} = 0V	T _J = 25°C	—	2.50	—	V
			T _J = 125°C	—	3.20	—	
			T _J = 150°C	—	3.30	3.80	
t _{rr}	Reverse recovery time (Note 2)	V _{CC} = 3600V I _C = 900A V _{GE} = ±15V R _{G(on)} =4.3Ω L _s = 150nH Inductive load	T _J = 25°C	—	2.00	—	μs
			T _J = 125°C	—	2.40	—	
			T _J = 150°C	—	2.50	—	
I _{rr}	Reverse recovery current (Note 2)		T _J = 25°C	—	1250	—	A
			T _J = 125°C	—	1200	—	
			T _J = 150°C	—	1200	—	
Q _{rr(10%)}	Reverse recovery charge (Note 2, 7)		T _J = 25°C	—	1800	—	μC
			T _J = 125°C	—	2300	—	
			T _J = 150°C	—	2400	—	
Q _{rr}	Reverse recovery charge (Note 2, 6)		T _J = 25°C	—	1850	—	μC
			T _J = 125°C	—	2350	—	
			T _J = 150°C	—	2500	—	
E _{rec(10%)}	Reverse recovery energy (per pulse) (Note 2, 5)	T _J = 25°C	—	2.90	—	J	
		T _J = 125°C	—	4.20	—		
		T _J = 150°C	—	4.50	—		
E _{rec}	Reverse recovery energy (per pulse) (Note 2, 6)	T _J = 25°C	—	3.00	—	J	
		T _J = 125°C	—	4.30	—		
		T _J = 150°C	—	4.80	—		

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$R_{th(j-c)Q}$	Thermal resistance	Junction to Case, IGBT part	—	—	10.0	K/kW
$R_{th(j-c)D}$		Junction to Case, FWDi part	—	—	16.0	K/kW
$R_{th(c-s)}$	Contact thermal resistance	Case to heat sink, $\lambda_{grease} = 1W/m^2K$, $D_{(c-s)} = 80\mu m$	—	5.0	—	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
M_t	Mounting torque	M8 : Main terminals screw	7.0	—	19.0	N·m
M_s		M6 : Mounting screw	3.0	—	6.0	N·m
M_t		M4 : Auxiliary terminals screw	1.0	—	3.0	N·m
m	Mass		—	1.5	—	kg
CTI	Comparative tracking index		600	—	—	—
d_a	Clearance		26.0	—	—	mm
d_s	Creepage distance		56.0	—	—	mm
L_{PCE}	Parasitic stray inductance		—	13.5	—	nH
R_{CC+EE}	Internal lead resistance	$T_C = 25^\circ C$	—	0.12	—	mΩ

Note1. Pulse width and repetition rate should be such that junction temperature (T_J) does not exceed T_{Jopmax} rating.

Note2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

Note3. Junction temperature (T_J) should not exceed T_{Jmax} rating ($150^\circ C$).

Note4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

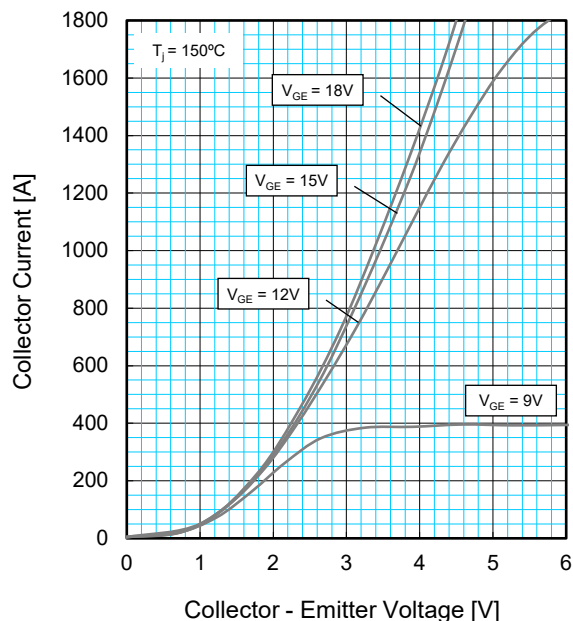
Note5. The integration range of switching energies is from $10\%V_{CE}$ to $10\%I_C(10\%I_E)$.

Note6. Definition of all items is according to IEC 60747, unless otherwise specified.

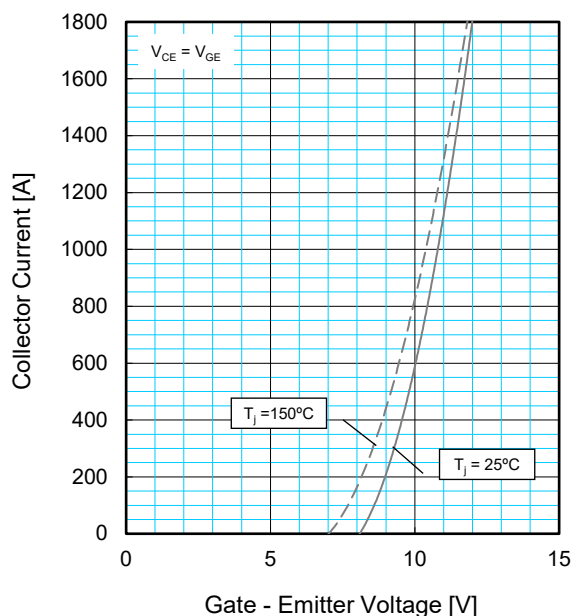
Note7. The integration range of reverse recovery charge is from $I_E = 0A$ to $10\%I_E$.

PERFORMANCE CURVES

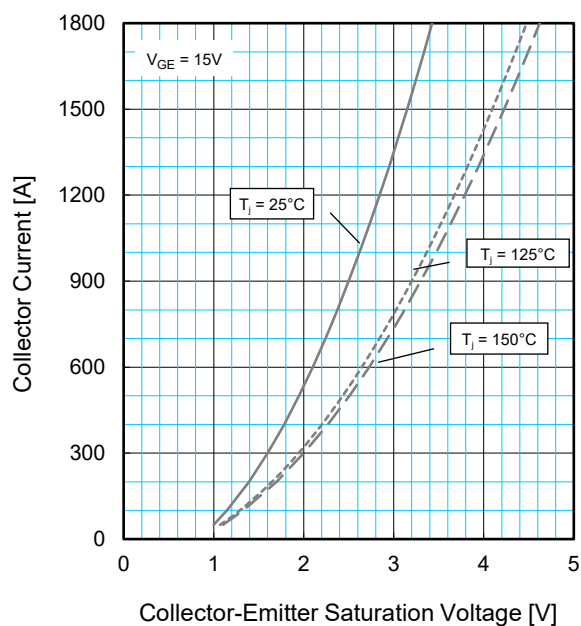
**OUTPUT CHARACTERISTICS
(TYPICAL)**



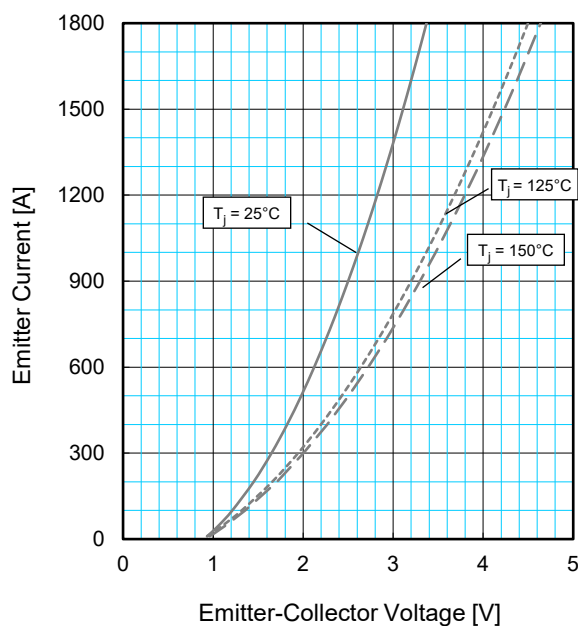
**TRANSFER CHARACTERISTICS
(TYPICAL)**



**COLLECTOR-EMITTER SATURATION VOLTAGE
CHARACTERISTICS (TYPICAL)**

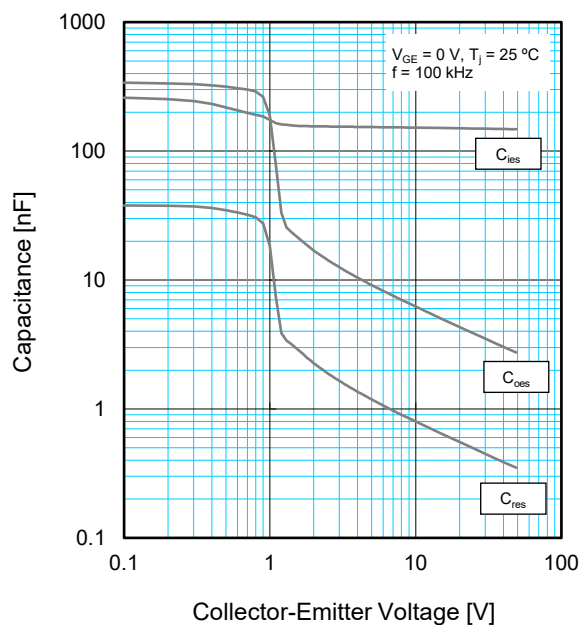


**FREE-WHEEL DIODE FORWARD
CHARACTERISTICS (TYPICAL)**

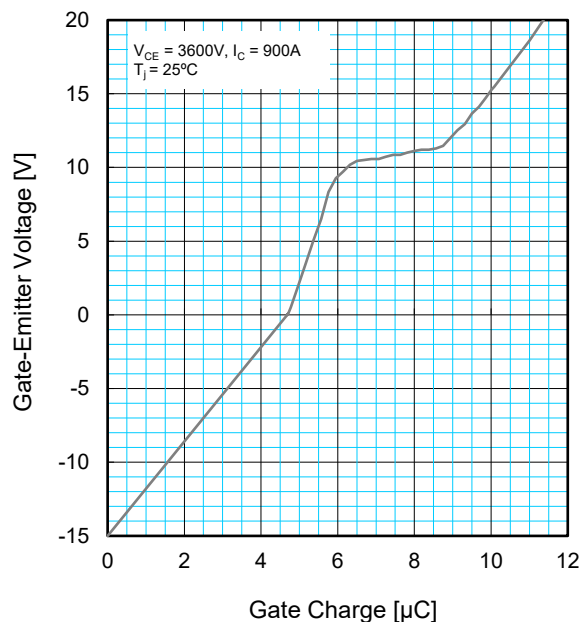


PERFORMANCE CURVES

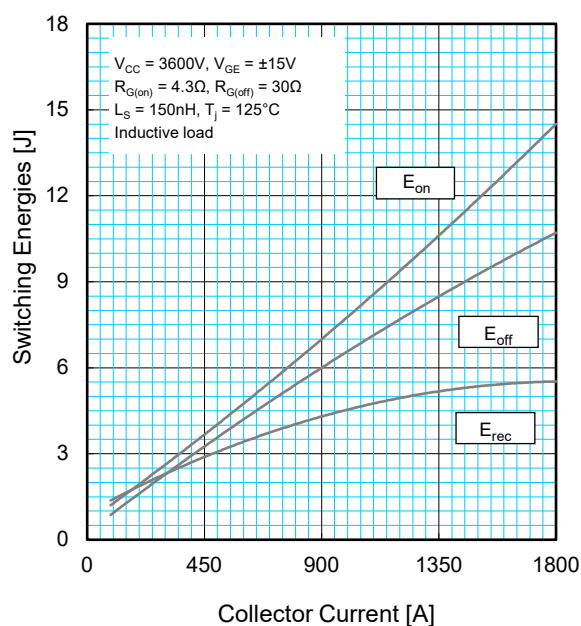
**CAPACITANCE CHARACTERISTICS
(TYPICAL)**



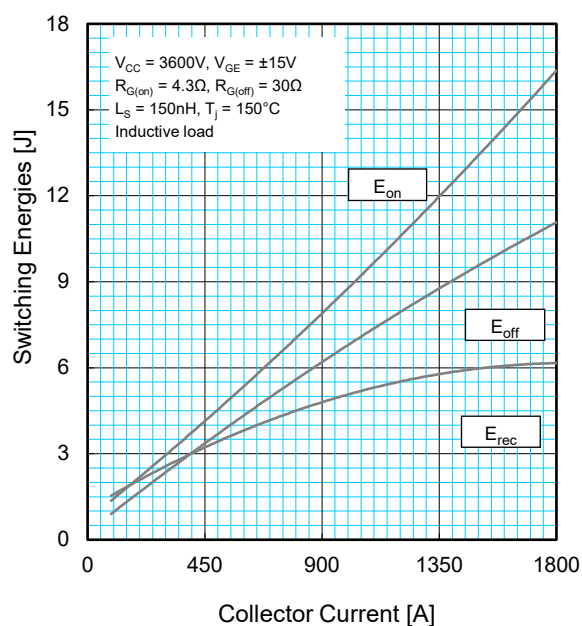
**GATE CHARGE CHARACTERISTICS
(TYPICAL)**



**HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS (TYPICAL)**

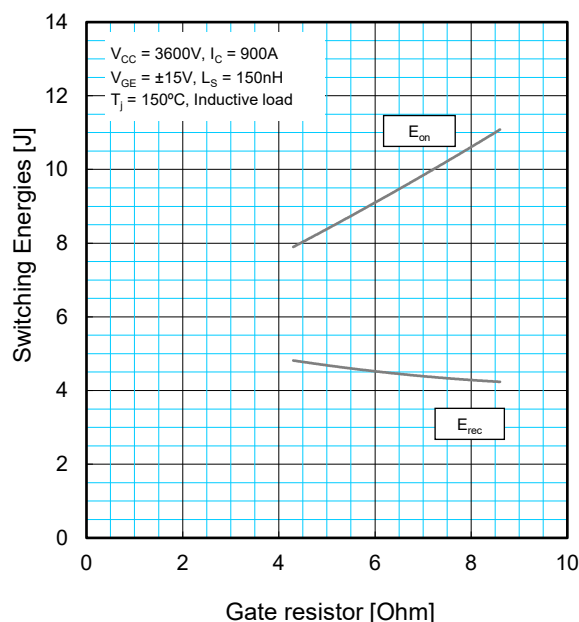


**HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS (TYPICAL)**

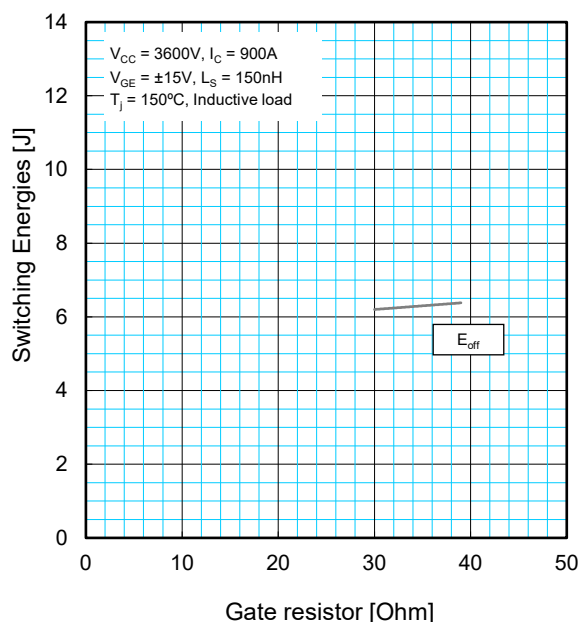


PERFORMANCE CURVES

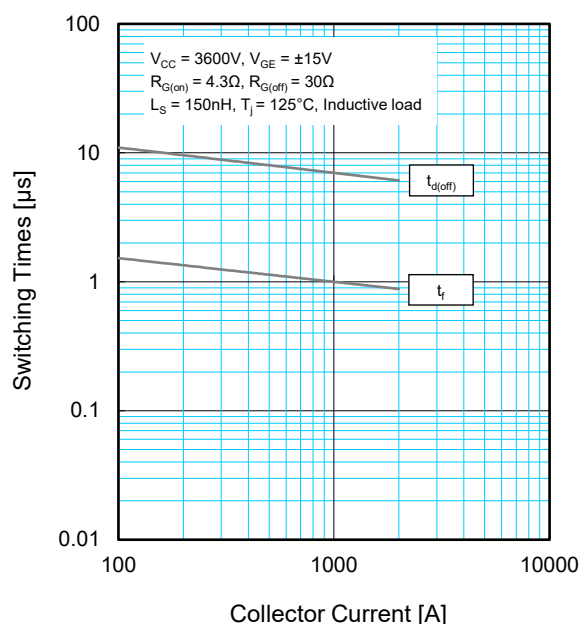
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



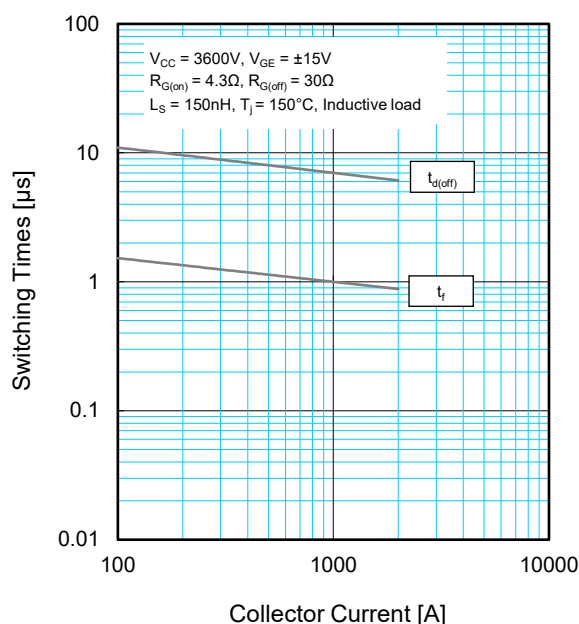
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

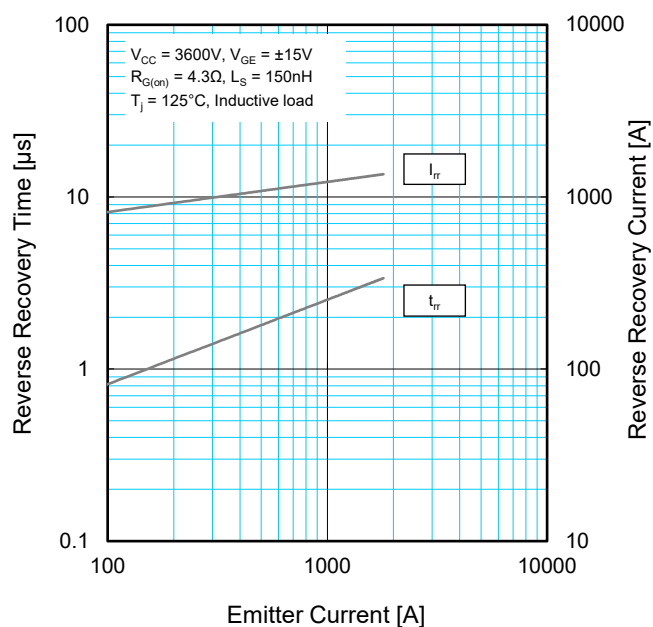
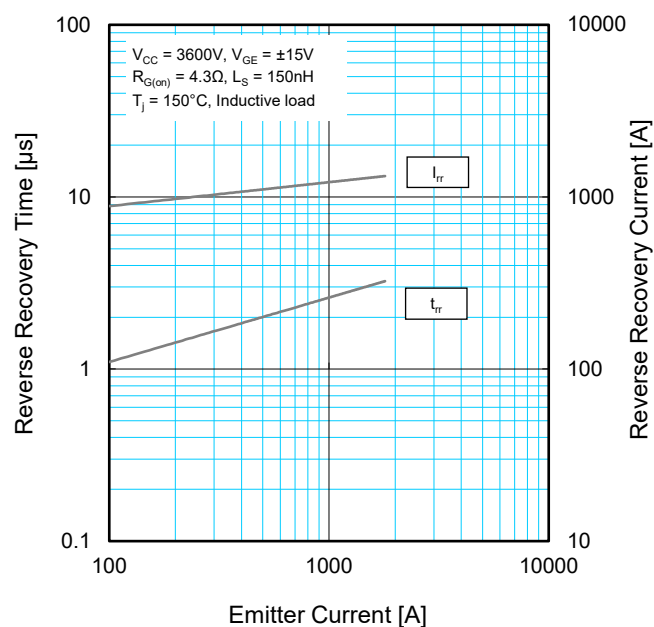
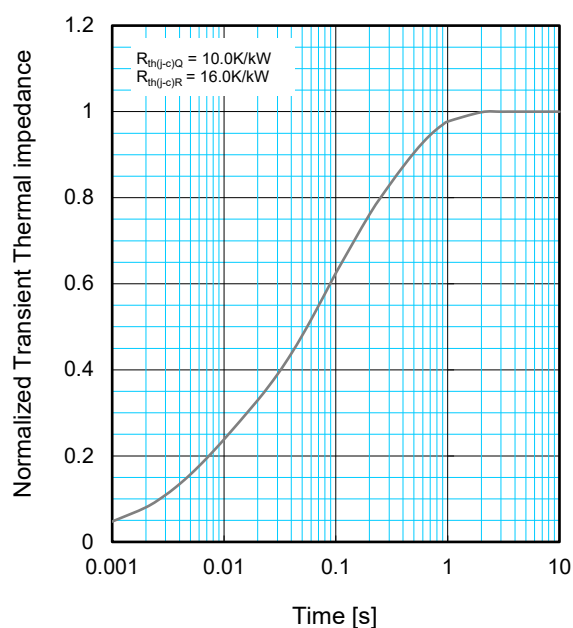


HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



PERFORMANCE CURVES**FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)****FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)****TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS**

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i \left\{ 1 - \exp\left(-\frac{t}{\tau_i}\right) \right\}$$

	1	2	3	4
$R_i / R_{th(j-c)}$	0.0096	0.1893	0.4044	0.3967
τ_i [sec]	0.0001	0.0058	0.0602	0.3512

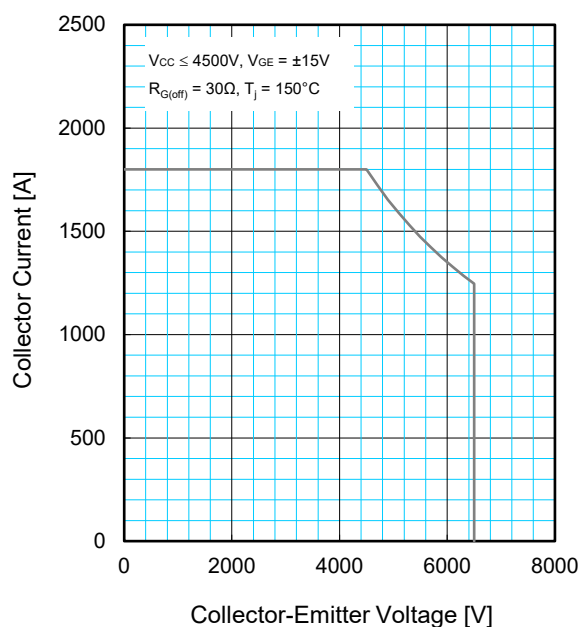
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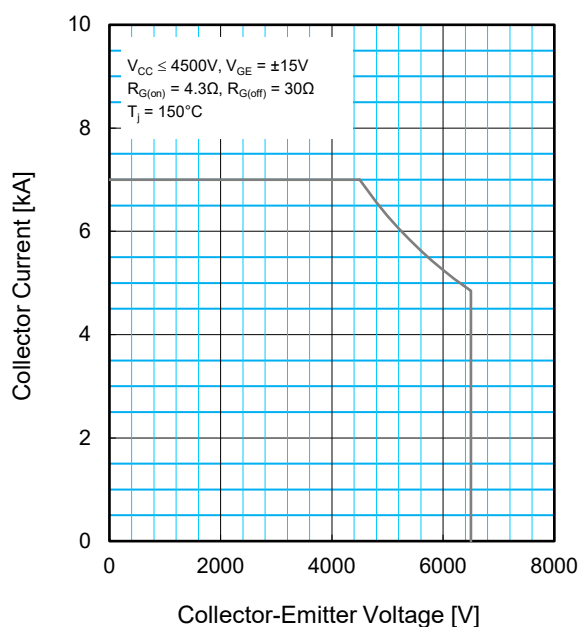
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PERFORMANCE CURVES

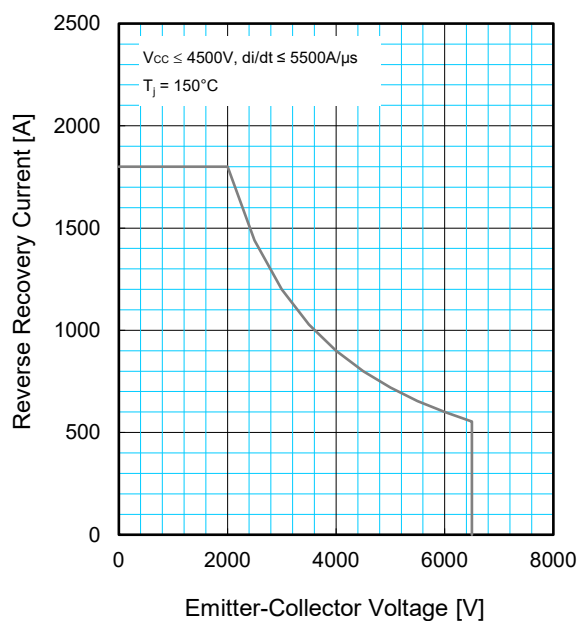
REVERSE BIAS SAFE OPERATING AREA (RBSOA)



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



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